



### Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
$V_{RRM}$	80 V to 200 V
$I_{FSM}$	50 A
$V_F$	0.85V
$T_j \text{ max.}$	150 °C



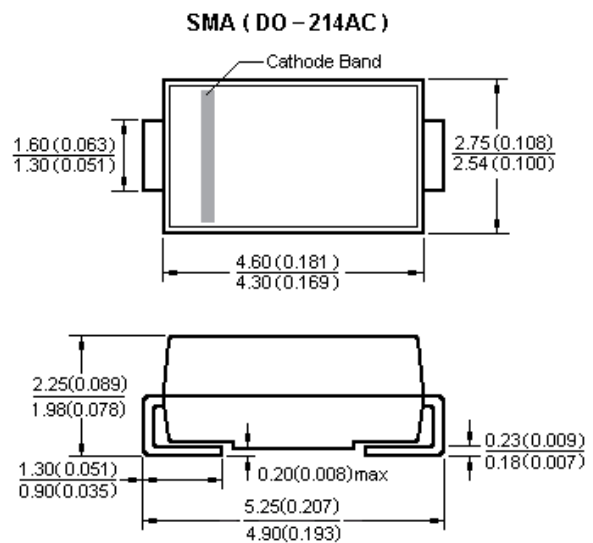
SMA (DO-214AC)

### Features

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:  
260°C/10 seconds at terminals
- Component in accordance to  
RoHS 2002/95/1 and WEEE 2002/96/EC

### Mechanical Date

- Case: JEDEC DO-214AC molded plastic body over passivated chip
- Terminals: Solder plated, solderable per  
J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end



Dimensions in millimeters and (inches)

### Maximum Ratings & Thermal Characteristics & Electrical Characteristics

( $T_A = 25\text{ °C}$  unless otherwise noted)

	Symbol	SS28	SS210	SS2150	SS2200	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	80	100	150	200	V
Maximum RMS voltage	$V_{RMS}$	56	70	105	140	V
Maximum DC blocking voltage	$V_{DC}$	80	100	150	200	V
Maximum average forward rectified current	$I_{F(AV)}$	2				A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	50				A
Maximum instantaneous forward voltage at 2.0A	$V_F$	0.85				V
Maximum DC reverse current at Rated DC blocking voltage	$I_R$	$T_A = 25\text{ °C}$	0.5			mA
		$T_A = 100\text{ °C}$	5			mA
Voltage rate of change (rated VR)	dv/dt	10000				V/ $\mu$ s
Thermal resistance from junction to ambient	$R_{\theta JA}$	88				°C/W
Operating junction and storage temperature range	$T_J, T_{STG}$	- 65 to +150				°C